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**CONSTRUCTIONAL ANALYSIS FOR QFN STACKED DIE FAILURE IDENTIFICATION**

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**ABSTRACT**

The electronic industry has always set for the highest standards in quality and reliability. To ensure the reliability of final semiconductor products, evaluation and characterization at process development and product stage are conducted. In this paper, constructional analysis (CA) technique is used as a tool to determine failure mode in QFN stacked die package that will affect reliability. The procedure in CA involves package decapsulation, cross sectioning

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